

Exhibit 1

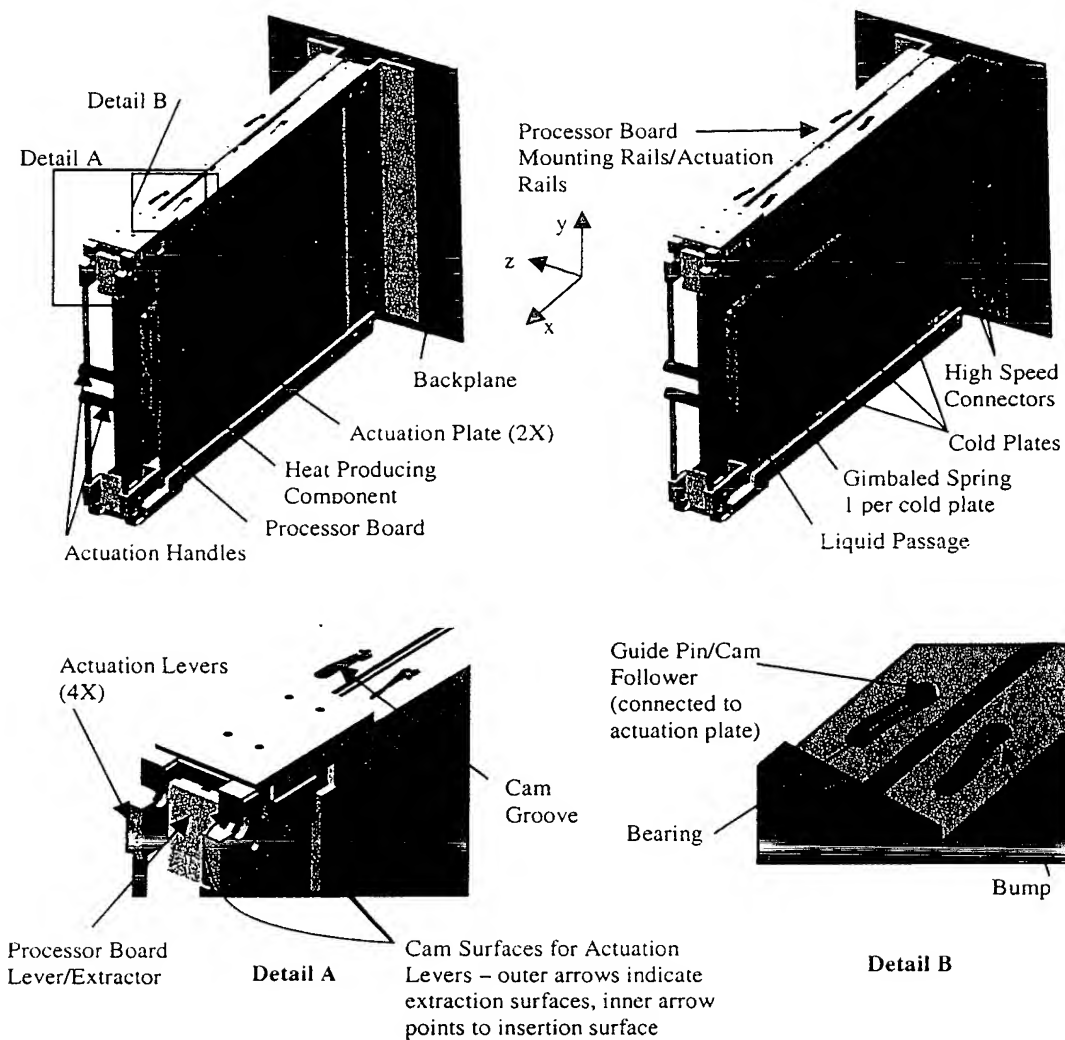


Figure 3. Mechanically Actuated Thermal Connector Assembly

Allen C. Smith 6/21/00
C. Smith 6/19/00
Allen 6/19/00



Exhibit 2



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December 4, 2000

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RE: Preparation of Patent Application

↓
Redacted
↑

HP Reference No.: 10005107.

Entitled: Mechanically Actuated Thermal Connector For Cooling Electronics

HP Required Date: February 22, 2001

Dear James:

We would like you to provide a quote of the cost for your firm to prepare a US Patent application based on the HP Invention Disclosure identified above, a copy of which is enclosed.

Redacted

Sincerely,

Lloyd E. Dakin, Jr.

Enc.: HP Invention Disclosure
RFQ
Outside Counsel Checklist

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